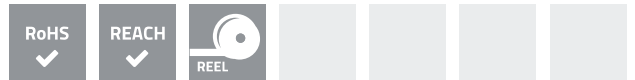


SMD contact springs are ideal for automatic assembly on printed circuit boards. They are soldered by the standard-reflow-soldering process.

The standard basic material used for SMD contact springs is copper beryllium (CuBe). However, other materials can also be supplied.

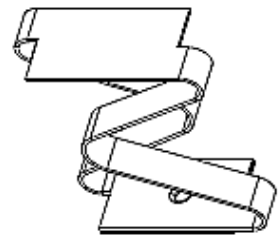
As standard, SMD springs are gold-plated (AU). They can be supplied in a wide range of dimensions and shapes.

- Ideal for automatic assembly
- Standard basic material: CuBe
- Standard plating: AU
- Available in different dimensions and types
- Almost unlimited working life

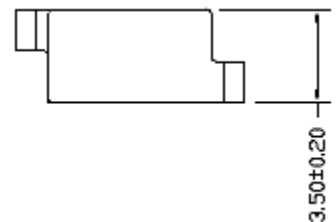
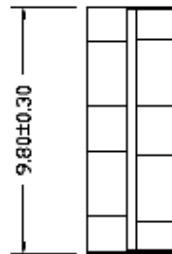
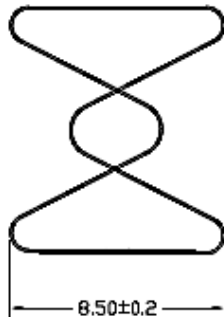
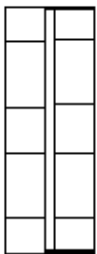


PRODUCT SPECIFICATIONS

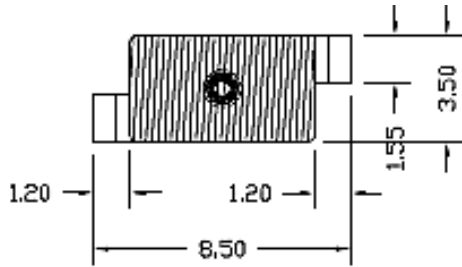
PROPERTY		VALUE / TOLERANCE
Thickness		0,1 mm
Width		3,5 mm ± 0,2
Length		8,5 mm ± 0,2
Height		9,8 mm ± 0,2
Basic material		Copper beryllium (CuBe)
Plating	Barrier layer NI Outer layer AU	1µm – 2µm 0,025µm – 0,075µm



DIMENSIONS (mm)

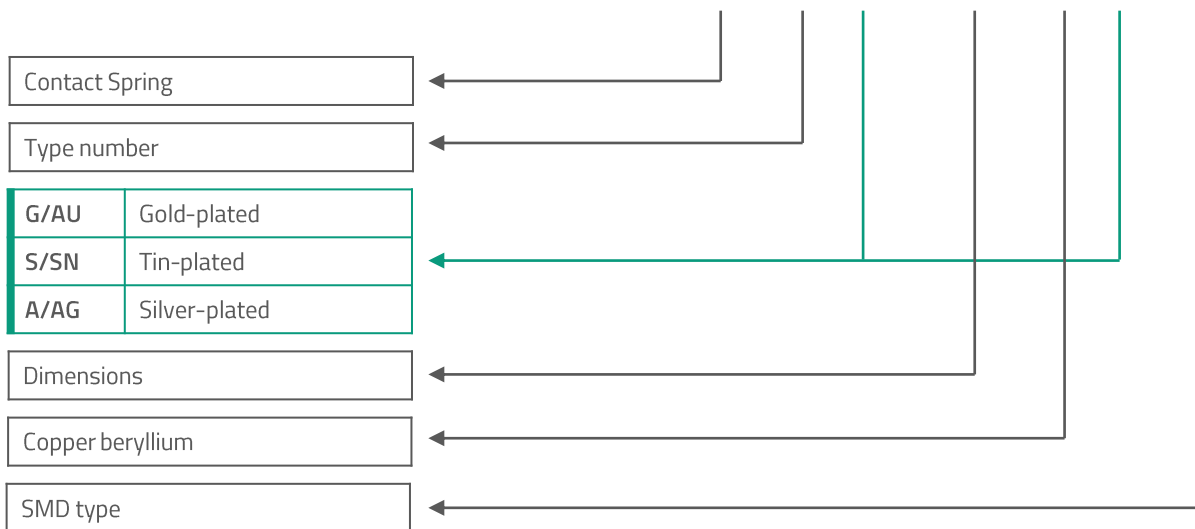


RECOMMENDED PAD FOR THE PCB (mm)



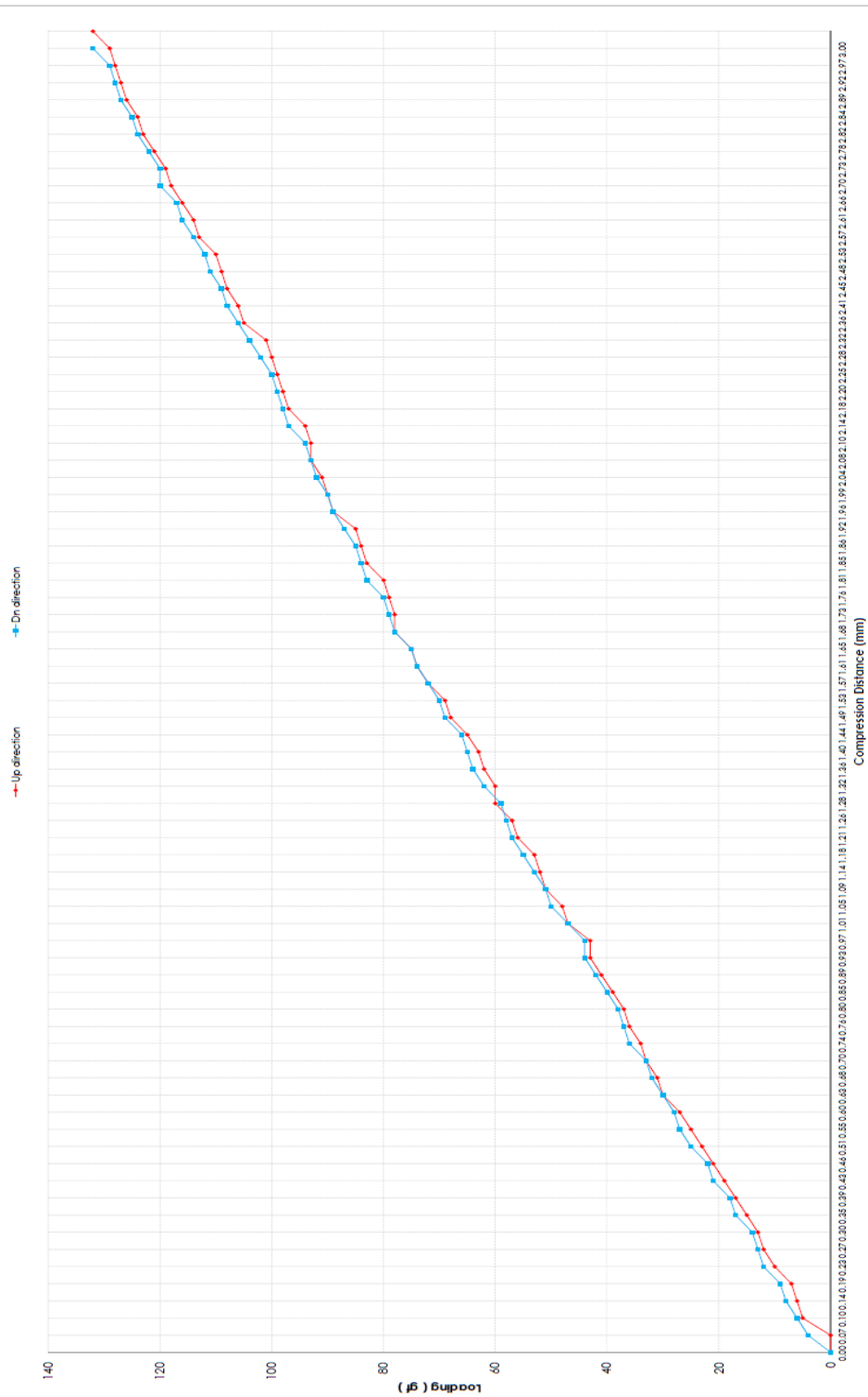
BUILDING AN ITEM NUMBER

FCB-14XX3585098B-YY-SMD



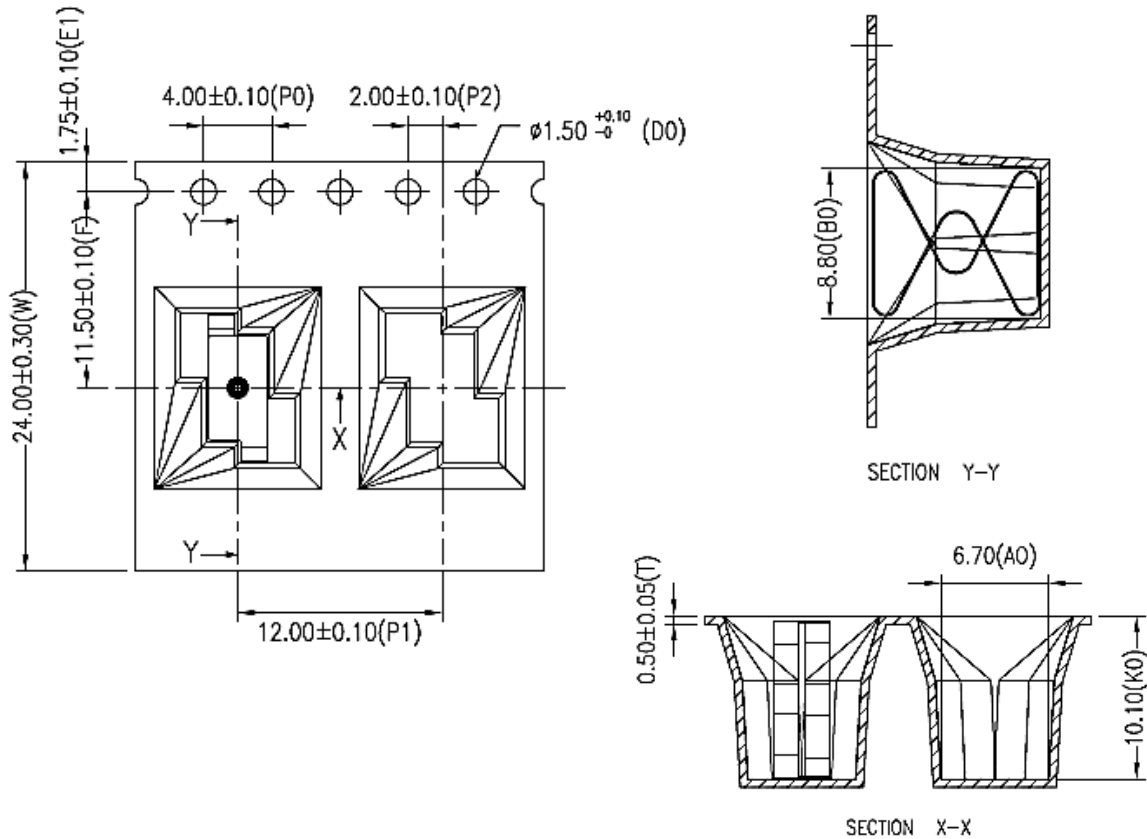
Standard options

FORCE DEFLECTION DIAGRAM*



NOTE | * Only valid for gold-plated version

PACKING SPECIFICATION – TAPE AND REEL (mm)



	A ₀	B ₀	K ₀
	6,70	8,80	10,10
Tolerance	± 0,20	± 0,20	+ 0,30 - 0,00

- Part conforms to EIA-481-D standards.
- All dimensions in mm unless otherwise stated.
- Material: Transparent polystyrene
- Component packing to 13" reel: 500 pcs.

Modifications and errors excepted. The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assume legal responsibility. Users should undertake sufficient verifications and testings to determine the suitability for their own particular purpose of any information or products referred to herein.